

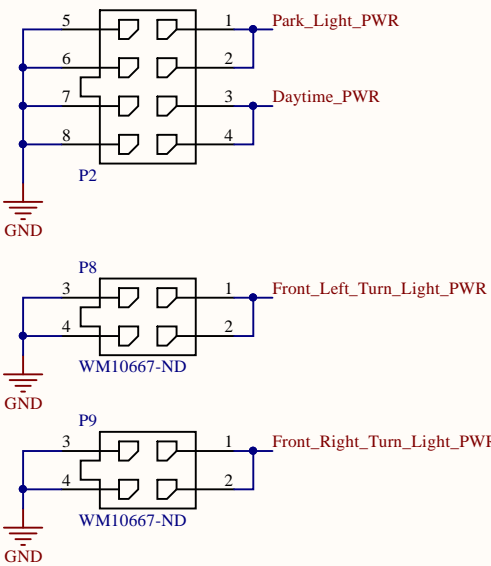
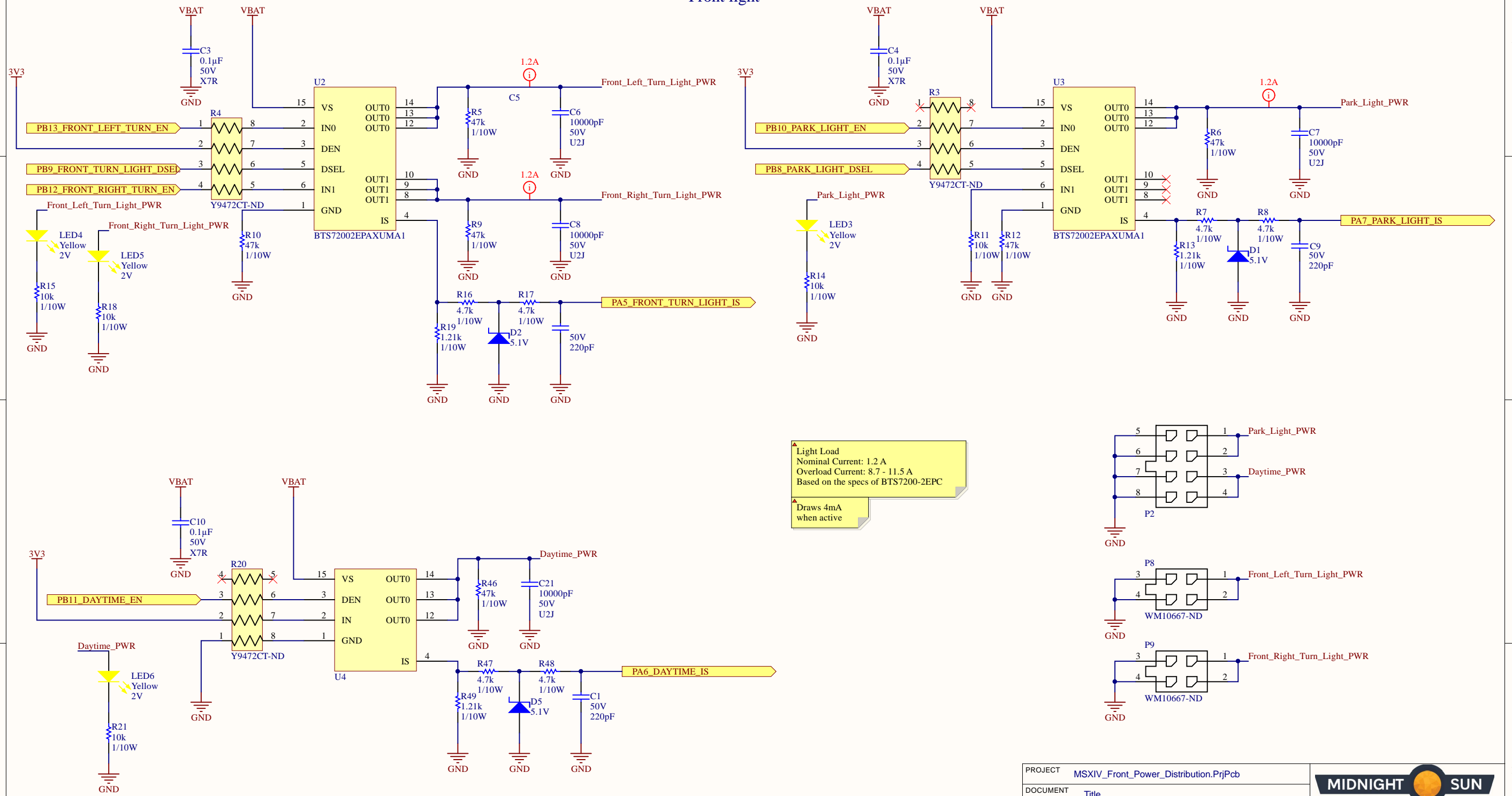
PROJECTMSXIV_Front_Power_Distribution.PrjPcb	
DOCUMENTController Board Interface	
PART NUMBER	VARIANT[No Variations]
DRAWN BY	REVISION
LAST MODIFIED2020-01-20	SHEET * OF *

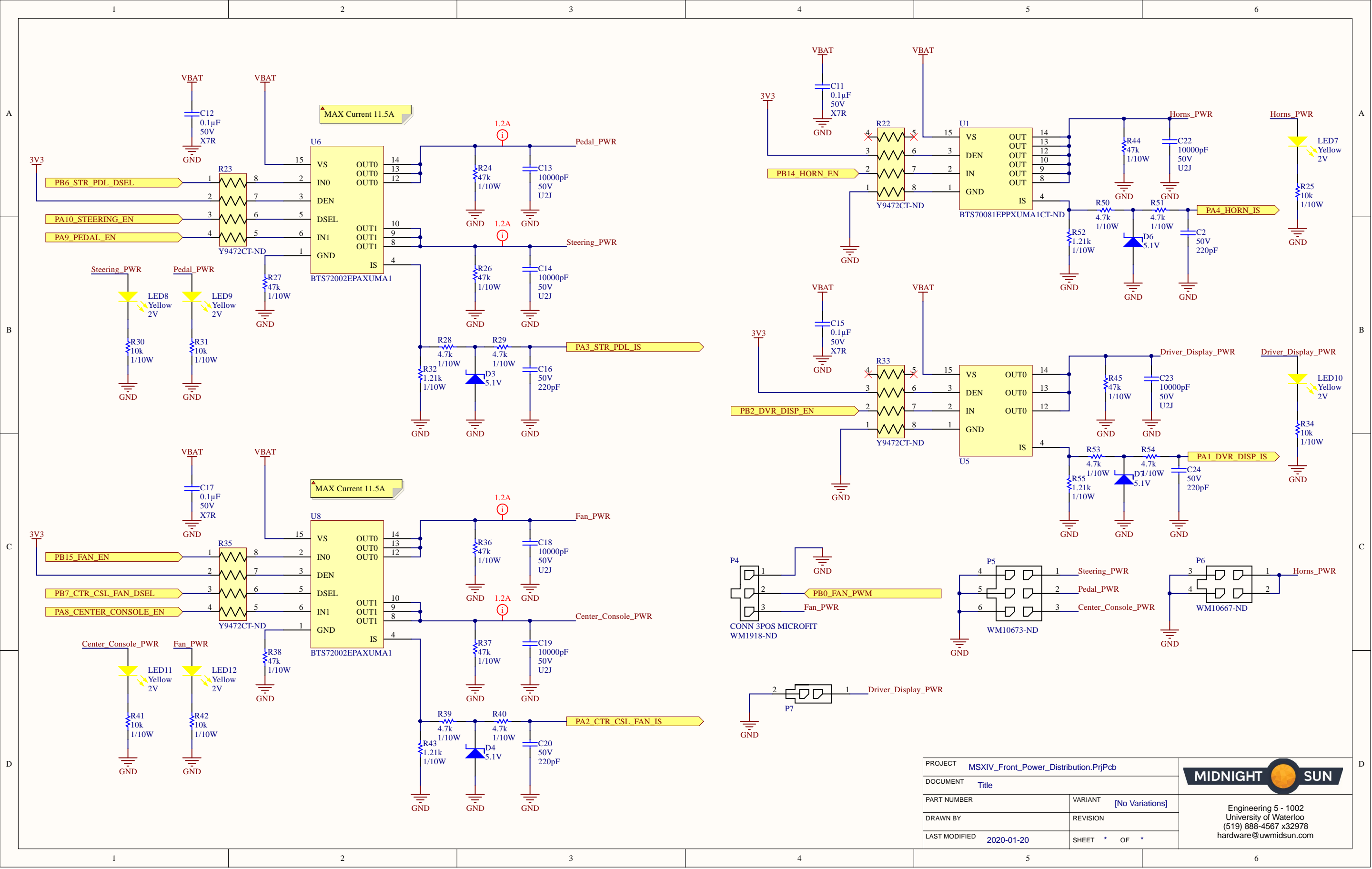
MIDNIGHT

SUN

Engineering 5 - 1002
University of Waterloo
(519) 888-4567 x32978
hardware@uwmidsun.com

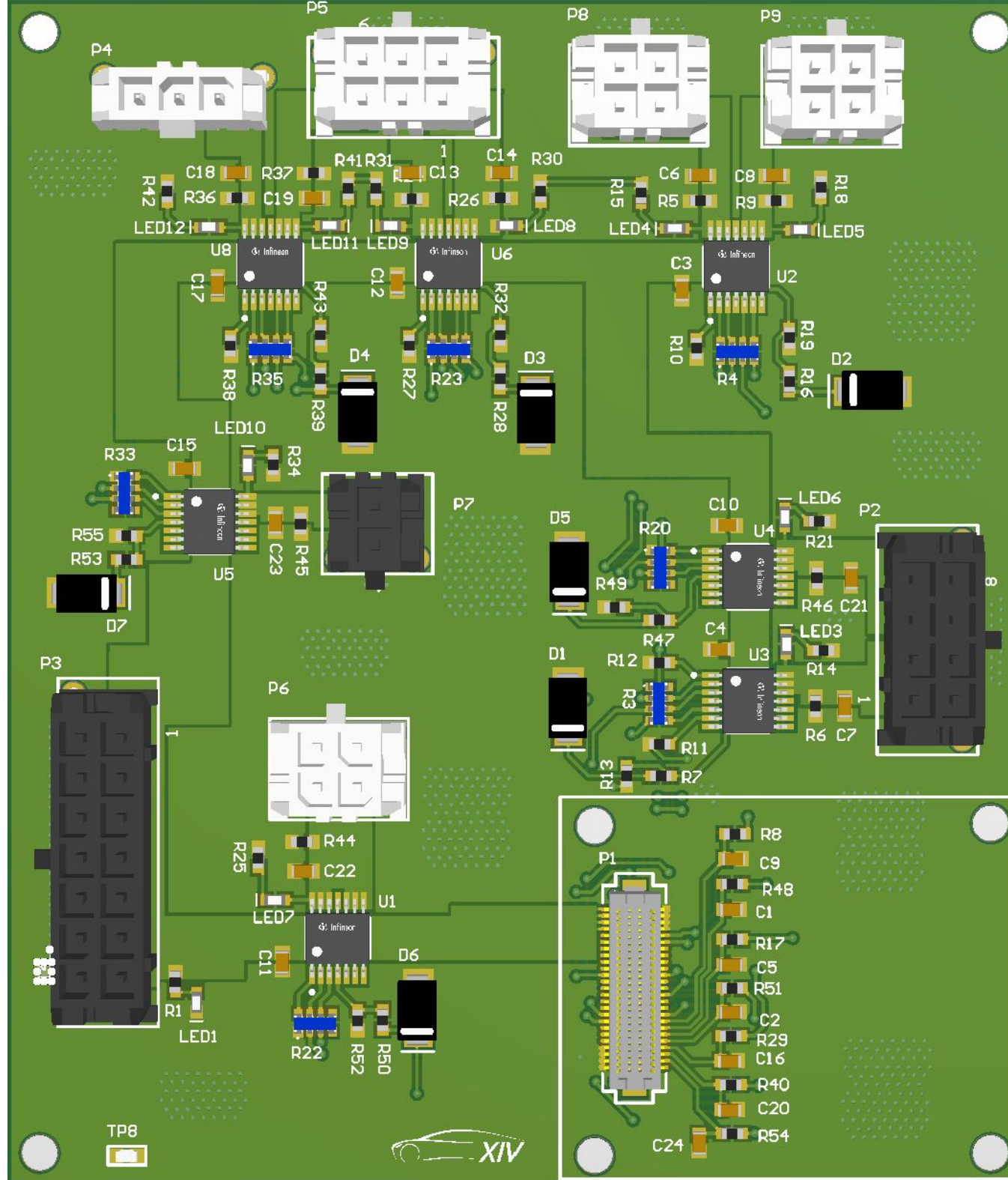
Front light

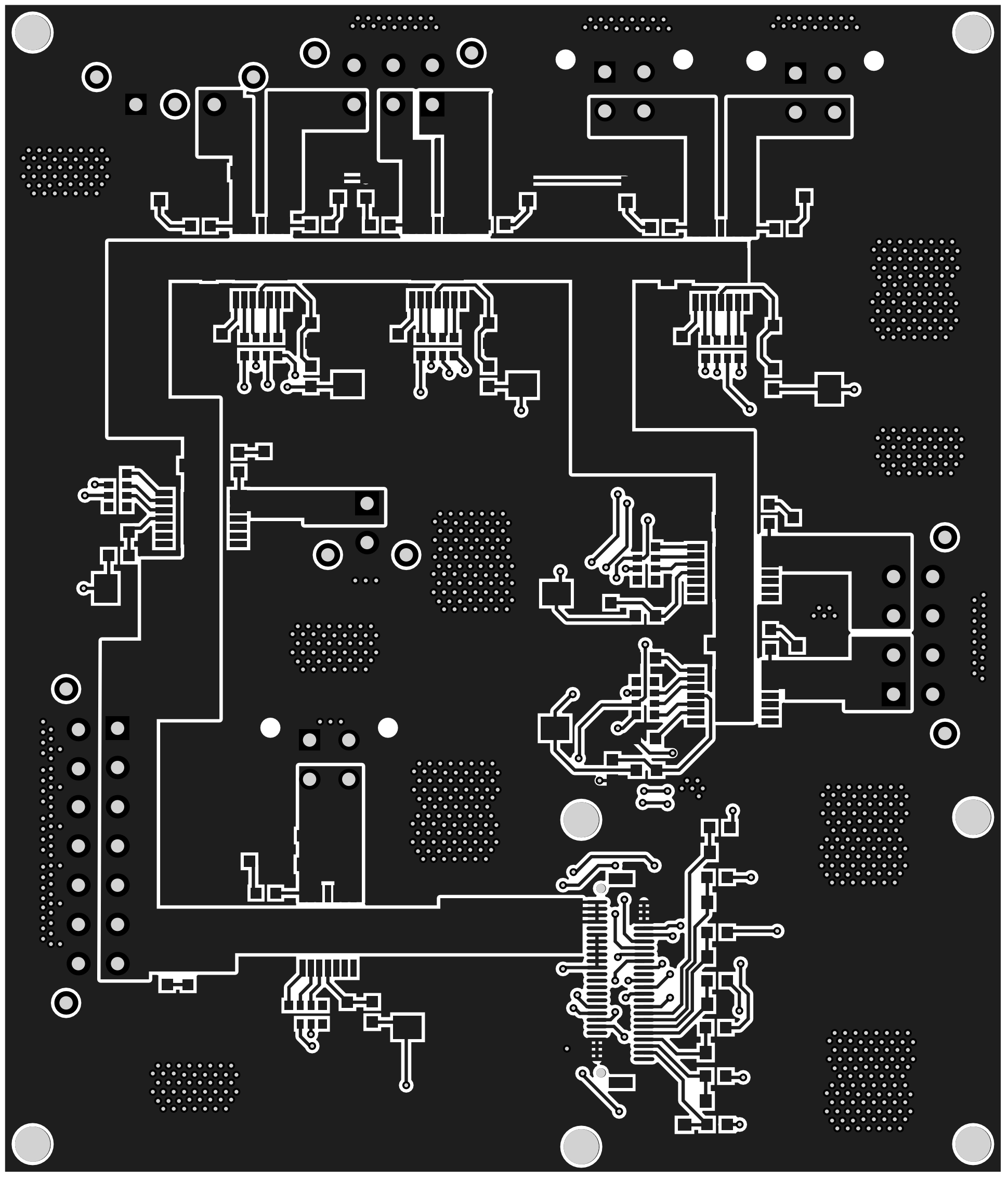


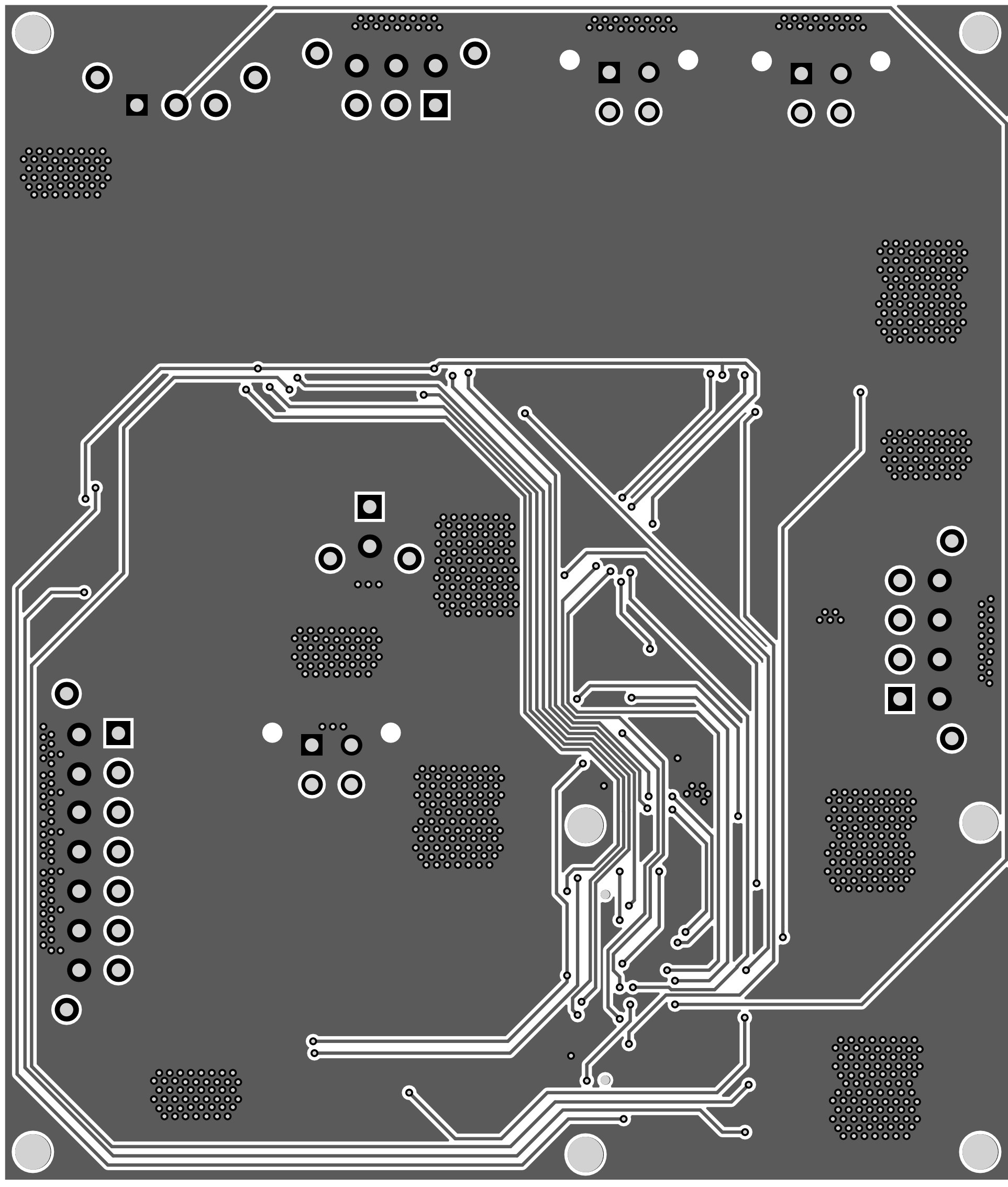


Bill of Materials	
Project:	ISXIV_Front_Pow er_Distribution.PrjPc
Revision:	<Parameter ProjectRevision not found>
Project Lead:	<Parameter ProjectAuthor not found>
Generated On:	2020-01-20 9:49 PM
Production Quantity:	1
Currency	CAD
Total Parts Count:	113

[illegible]







Design Rules Verification Report

Filename : D:\Josh9\Documents\Midnight Sun\hardware\MSXIV_FrontPowerDistribution\Fr

Warnings 0
Rule Violations 189

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.152mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.254mm) (Max=0.254mm) (Preferred=0.254mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	7
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	128
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	54
Silk to Silk (Clearance=0.254mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Preferred=12.7mm) (All)	0
Total	189

Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(2.5mm,2.5mm) on Multi-Layer Actual Hole Size = 2.7mm	
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(2.5mm,87.5mm) on Multi-Layer Actual Hole Size = 2.7mm	
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(44.5mm,2.3mm) on Multi-Layer Actual Hole Size = 2.7mm	
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(44.5mm,27.3mm) on Multi-Layer Actual Hole Size = 2.7mm	
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(74.5mm,2.5mm) on Multi-Layer Actual Hole Size = 2.7mm	
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(74.5mm,27.5mm) on Multi-Layer Actual Hole Size = 2.7mm	
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(74.5mm,87.5mm) on Multi-Layer Actual Hole Size = 2.7mm	

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)

Minimum Solder Mask Sliver Constraint: (0.105mm < 0.254mm) Between Pad P1-(46mm,22.05mm) on Multi-Layer And Pad P1-(47.5mm,22.8mm) on Top
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.254mm) Between Pad P1-(46mm,7.95mm) on Multi-Layer And Pad P1-(47.5mm,7.2mm) on Top
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R20-1(48.8mm,48.18mm) on Top Layer And Pad R20-2(48.8mm,47.3mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R20-2(48.8mm,47.3mm) on Top Layer And Pad R20-3(48.8mm,46.5mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R20-3(48.8mm,46.5mm) on Top Layer And Pad R20-4(48.8mm,45.62mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R20-5(50.2mm,45.62mm) on Top Layer And Pad R20-6(50.2mm,46.5mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R20-6(50.2mm,46.5mm) on Top Layer And Pad R20-7(50.2mm,47.3mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R20-7(50.2mm,47.3mm) on Top Layer And Pad R20-8(50.2mm,48.18mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R22-1(22.12mm,11.7mm) on Top Layer And Pad R22-2(23mm,11.7mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R22-2(23mm,11.7mm) on Top Layer And Pad R22-3(23.8mm,11.7mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R22-3(23.8mm,11.7mm) on Top Layer And Pad R22-4(24.68mm,11.7mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R22-5(24.68mm,13.1mm) on Top Layer And Pad R22-6(23.8mm,13.1mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R22-6(23.8mm,13.1mm) on Top Layer And Pad R22-7(23mm,13.1mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R22-7(23mm,13.1mm) on Top Layer And Pad R22-8(22.12mm,13.1mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R23-1(32.22mm,62.8mm) on Top Layer And Pad R23-2(33.1mm,62.8mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R23-2(33.1mm,62.8mm) on Top Layer And Pad R23-3(33.9mm,62.8mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R23-3(33.9mm,62.8mm) on Top Layer And Pad R23-4(34.78mm,62.8mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R23-5(34.78mm,64.2mm) on Top Layer And Pad R23-6(33.9mm,64.2mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R23-6(33.9mm,64.2mm) on Top Layer And Pad R23-7(33.1mm,64.2mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R23-7(33.1mm,64.2mm) on Top Layer And Pad R23-8(32.22mm,64.2mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R3-1(48.7mm,37.88mm) on Top Layer And Pad R3-2(48.7mm,37mm) on Top
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R3-2(48.7mm,37mm) on Top Layer And Pad R3-3(48.7mm,36.2mm) on Top
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R3-3(48.7mm,36.2mm) on Top Layer And Pad R3-4(48.7mm,35.32mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R33-1(8.3mm,53.8mm) on Top Layer And Pad R33-2(8.3mm,52.92mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R33-2(8.3mm,52.92mm) on Top Layer And Pad R33-3(8.3mm,52.12mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R33-3(8.3mm,52.12mm) on Top Layer And Pad R33-4(8.3mm,51.24mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R33-5(9.7mm,51.24mm) on Top Layer And Pad R33-6(9.7mm,52.12mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R33-6(9.7mm,52.12mm) on Top Layer And Pad R33-7(9.7mm,52.92mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R33-7(9.7mm,52.92mm) on Top Layer And Pad R33-8(9.7mm,53.8mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R3-5(50.1mm,35.32mm) on Top Layer And Pad R3-6(50.1mm,36.2mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R35-1(18.72mm,62.8mm) on Top Layer And Pad R35-2(19.6mm,62.8mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R35-2(19.6mm,62.8mm) on Top Layer And Pad R35-3(20.4mm,62.8mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R35-3(20.4mm,62.8mm) on Top Layer And Pad R35-4(21.28mm,62.8mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R35-5(21.28mm,64.2mm) on Top Layer And Pad R35-6(20.4mm,64.2mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R35-6(20.4mm,64.2mm) on Top Layer And Pad R35-7(19.6mm,64.2mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R35-7(19.6mm,64.2mm) on Top Layer And Pad R35-8(18.72mm,64.2mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R3-6(50.1mm,36.2mm) on Top Layer And Pad R3-7(50.1mm,37mm) on Top
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R3-7(50.1mm,37mm) on Top Layer And Pad R3-8(50.1mm,37.88mm) on Top
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R4-1(54.02mm,62.6mm) on Top Layer And Pad R4-2(54.9mm,62.6mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R4-2(54.9mm,62.6mm) on Top Layer And Pad R4-3(55.7mm,62.6mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R4-3(55.7mm,62.6mm) on Top Layer And Pad R4-4(56.58mm,62.6mm) or
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R4-5(56.58mm,64mm) on Top Layer And Pad R4-6(55.7mm,64mm) on Top
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R4-6(55.7mm,64mm) on Top Layer And Pad R4-7(54.9mm,64mm) on Top
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R4-7(54.9mm,64mm) on Top Layer And Pad R4-8(54.02mm,64mm) on Top
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-1(23.15mm,15.95mm) on Top Layer And Pad U1-2(23.8mm,15.95mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-10(25.75mm,21.65mm) on Top Layer And Pad U1-11(25.1mm,21.65mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-10(25.75mm,21.65mm) on Top Layer And Pad U1-9(26.4mm,21.65mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-11(25.1mm,21.65mm) on Top Layer And Pad U1-12(24.45mm,21.65mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-12(24.45mm,21.65mm) on Top Layer And Pad U1-13(23.8mm,21.65mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-13(23.8mm,21.65mm) on Top Layer And Pad U1-14(23.15mm,21.65mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-2(23.8mm,15.95mm) on Top Layer And Pad U1-3(24.45mm,15.95mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-3(24.45mm,15.95mm) on Top Layer And Pad U1-4(25.1mm,15.95mm) or

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-4(25.1mm, 15.95mm) on Top Layer And Pad U1-5(25.75mm, 15.95mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-5(25.75mm, 15.95mm) on Top Layer And Pad U1-6(26.4mm, 15.95mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-6(26.4mm, 15.95mm) on Top Layer And Pad U1-7(27.05mm, 15.95mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-8(27.05mm, 21.65mm) on Top Layer And Pad U1-9(26.4mm, 21.65mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-1(53.25mm, 66.85mm) on Top Layer And Pad U2-2(53.9mm, 66.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-10(55.85mm, 72.55mm) on Top Layer And Pad U2-11(55.2mm, 72.55mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-10(55.85mm, 72.55mm) on Top Layer And Pad U2-9(56.5mm, 72.55mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-11(55.2mm, 72.55mm) on Top Layer And Pad U2-12(54.55mm, 72.55mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-12(54.55mm, 72.55mm) on Top Layer And Pad U2-13(53.9mm, 72.55mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-13(53.9mm, 72.55mm) on Top Layer And Pad U2-14(53.25mm, 72.55mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-2(53.9mm, 66.85mm) on Top Layer And Pad U2-3(54.55mm, 66.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-3(54.55mm, 66.85mm) on Top Layer And Pad U2-4(55.2mm, 66.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-4(55.2mm, 66.85mm) on Top Layer And Pad U2-5(55.85mm, 66.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-5(55.85mm, 66.85mm) on Top Layer And Pad U2-6(56.5mm, 66.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-6(56.5mm, 66.85mm) on Top Layer And Pad U2-7(57.15mm, 66.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U2-8(57.15mm, 72.55mm) on Top Layer And Pad U2-9(56.5mm, 72.55mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-1(53.25mm, 38.737mm) on Top Layer And Pad U3-2(53.25mm, 38.087mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-10(58.95mm, 36.137mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-10(58.95mm, 36.137mm) on Top Layer And Pad U3-9(58.95mm, 35.487mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-11(58.95mm, 36.787mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-12(58.95mm, 37.437mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-13(58.95mm, 38.087mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-2(53.25mm, 38.087mm) on Top Layer And Pad U3-3(53.25mm, 37.437mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-3(53.25mm, 37.437mm) on Top Layer And Pad U3-4(53.25mm, 36.787mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-4(53.25mm, 36.787mm) on Top Layer And Pad U3-5(53.25mm, 36.137mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-5(53.25mm, 36.137mm) on Top Layer And Pad U3-6(53.25mm, 35.487mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-6(53.25mm, 35.487mm) on Top Layer And Pad U3-7(53.25mm, 34.837mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U3-8(58.95mm, 34.837mm) on Top Layer And Pad U3-9(58.95mm, 35.487mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-1(53.25mm, 48.15mm) on Top Layer And Pad U4-2(53.25mm, 47.5mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-10(58.95mm, 45.55mm) on Top Layer And Pad U4-11(58.95mm, 46.2mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-10(58.95mm, 45.55mm) on Top Layer And Pad U4-9(58.95mm, 44.9mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-11(58.95mm, 46.2mm) on Top Layer And Pad U4-12(58.95mm, 46.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-12(58.95mm, 46.85mm) on Top Layer And Pad U4-13(58.95mm, 47.5mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-13(58.95mm, 47.5mm) on Top Layer And Pad U4-14(58.95mm, 48.15mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-2(53.25mm, 47.5mm) on Top Layer And Pad U4-3(53.25mm, 46.85mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-3(53.25mm, 46.85mm) on Top Layer And Pad U4-4(53.25mm, 46.2mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-4(53.25mm, 46.2mm) on Top Layer And Pad U4-5(53.25mm, 45.55mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-5(53.25mm, 45.55mm) on Top Layer And Pad U4-6(53.25mm, 44.9mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-6(53.25mm, 44.9mm) on Top Layer And Pad U4-7(53.25mm, 44.25mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U4-8(58.95mm, 44.25mm) on Top Layer And Pad U4-9(58.95mm, 44.9mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-1(12.55mm, 52.294mm) on Top Layer And Pad U5-2(12.55mm, 51.644mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-10(18.25mm, 49.694mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-10(18.25mm, 49.694mm) on Top Layer And Pad U5-9(18.25mm, 49.044mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-11(18.25mm, 50.344mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-12(18.25mm, 50.994mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-13(18.25mm, 51.644mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-2(12.55mm, 51.644mm) on Top Layer And Pad U5-3(12.55mm, 50.994mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-3(12.55mm, 50.994mm) on Top Layer And Pad U5-4(12.55mm, 50.344mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-4(12.55mm, 50.344mm) on Top Layer And Pad U5-5(12.55mm, 49.694mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-5(12.55mm, 49.694mm) on Top Layer And Pad U5-6(12.55mm, 49.044mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-6(12.55mm, 49.044mm) on Top Layer And Pad U5-7(12.55mm, 48.394mm)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U5-8(18.25mm, 48.394mm) on Top Layer And Pad U5-9(18.25mm, 49.044mm)

Minimum Solder Mask Sliver (Gap=0.254mm) (All), (All)
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-1(31.55mm, 67.05mm) on Top Layer And Pad U6-2(32.2mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-10(34.15mm, 72.75mm) on Top Layer And Pad U6-11(33.5mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-10(34.15mm, 72.75mm) on Top Layer And Pad U6-9(34.8mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-11(33.5mm, 72.75mm) on Top Layer And Pad U6-12(32.85mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-12(32.85mm, 72.75mm) on Top Layer And Pad U6-13(32.2mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-13(32.2mm, 72.75mm) on Top Layer And Pad U6-14(31.55mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-2(32.2mm, 67.05mm) on Top Layer And Pad U6-3(32.85mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-3(32.85mm, 67.05mm) on Top Layer And Pad U6-4(33.5mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-4(33.5mm, 67.05mm) on Top Layer And Pad U6-5(34.15mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-5(34.15mm, 67.05mm) on Top Layer And Pad U6-6(34.8mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-6(34.8mm, 67.05mm) on Top Layer And Pad U6-7(35.45mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U6-8(35.45mm, 72.75mm) on Top Layer And Pad U6-9(34.8mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-1(18.05mm, 67.05mm) on Top Layer And Pad U8-2(18.7mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-10(20.65mm, 72.75mm) on Top Layer And Pad U8-11(20mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-10(20.65mm, 72.75mm) on Top Layer And Pad U8-9(21.3mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-11(20mm, 72.75mm) on Top Layer And Pad U8-12(19.35mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-12(19.35mm, 72.75mm) on Top Layer And Pad U8-13(18.7mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-13(18.7mm, 72.75mm) on Top Layer And Pad U8-14(18.05mm, 72.75mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-2(18.7mm, 67.05mm) on Top Layer And Pad U8-3(19.35mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-3(19.35mm, 67.05mm) on Top Layer And Pad U8-4(20mm, 67.05mm) on Top
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-4(20mm, 67.05mm) on Top Layer And Pad U8-5(20.65mm, 67.05mm) on Top
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-5(20.65mm, 67.05mm) on Top Layer And Pad U8-6(21.3mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-6(21.3mm, 67.05mm) on Top Layer And Pad U8-7(21.95mm, 67.05mm) or
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U8-8(21.95mm, 72.75mm) on Top Layer And Pad U8-9(21.3mm, 72.75mm) or

Silk To Solder Mask (Clearance=0.254mm) (IsPad).(All)

Silk To Solder Mask Clearance Constraint: (0.012mm < 0.254mm) Between Arc (18.662mm,62.338mm) on Top Overlay And Pad R35-1(18.72mm,62.8mm)
Silk To Solder Mask Clearance Constraint: (0.012mm < 0.254mm) Between Arc (22.062mm,11.238mm) on Top Overlay And Pad R22-1(22.12mm,11.7mm)
Silk To Solder Mask Clearance Constraint: (0.012mm < 0.254mm) Between Arc (32.162mm,62.338mm) on Top Overlay And Pad R23-1(32.22mm,62.8mm)
Silk To Solder Mask Clearance Constraint: (0.169mm < 0.254mm) Between Arc (48.238mm,37.938mm) on Top Overlay And Pad R3-1(48.7mm,37.88mm)
Silk To Solder Mask Clearance Constraint: (0.169mm < 0.254mm) Between Arc (48.338mm,48.238mm) on Top Overlay And Pad R20-1(48.8mm,48.18mm)
Silk To Solder Mask Clearance Constraint: (0.012mm < 0.254mm) Between Arc (53.962mm,62.138mm) on Top Overlay And Pad R4-1(54.02mm,62.6mm)
Silk To Solder Mask Clearance Constraint: (0.169mm < 0.254mm) Between Arc (7.838mm,53.858mm) on Top Overlay And Pad R33-1(8.3mm,53.8mm) or
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Pad C13-1(31.275mm,76.8mm) on Top Layer And Text "R24"
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Pad C13-2(29.925mm,76.8mm) on Top Layer And Text "R24"
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad C13-2(29.925mm,76.8mm) on Top Layer And Text "R31" (27.3mm,77.4mm)
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D1-2(42.5mm,34.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D2-2(63.489mm,60.225mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D3-2(40mm,60.536mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D4-2(26.6mm,60.6mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D5-2(42.6mm,44.6mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D6-2(31.2mm,11.436mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.247mm < 0.254mm) Between Pad D7-2(8.1mm,45mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED10-2(18.3mm,55.4mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED11-2(25.25mm,72.81mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED1-2(14.4mm,13.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED12-2(14.6mm,72.7mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED3-2(58.99mm,41.85mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED4-2(49.8mm,72.6mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED5-2(60.8mm,72.5mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED6-2(58.89mm,51.45mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED7-2(19.6mm,21.7mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED8-2(38.65mm,72.81mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.209mm < 0.254mm) Between Pad LED9-2(28.35mm,72.79mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.223mm < 0.254mm) Between Pad P1-1(49.3mm,21mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.223mm < 0.254mm) Between Pad P1-25(49.3mm,9mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.239mm < 0.254mm) Between Pad P1-26(45.7mm,9mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.239mm < 0.254mm) Between Pad P1-50(45.7mm,21mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.187mm < 0.254mm) Between Pad P2-0(72.34mm,33.9mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.236mm < 0.254mm) Between Pad P2-0(72.34mm,33.9mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.252mm < 0.254mm) Between Pad P2-0(72.34mm,48.9mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.236mm < 0.254mm) Between Pad P2-0(72.34mm,48.9mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.187mm < 0.254mm) Between Pad P3-0(5.06mm,13.3mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.236mm < 0.254mm) Between Pad P3-0(5.06mm,13.3mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.236mm < 0.254mm) Between Pad P3-0(5.06mm,37.3mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.252mm < 0.254mm) Between Pad P3-0(5.06mm,37.3mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.229mm < 0.254mm) Between Pad P5-0(24.1mm,85.94mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.236mm < 0.254mm) Between Pad P5-0(24.1mm,85.94mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.236mm < 0.254mm) Between Pad P5-0(36.1mm,85.94mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.213mm < 0.254mm) Between Pad P5-0(36.1mm,85.94mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.179mm < 0.254mm) Between Pad P7-0(25.1mm,47.56mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.147mm < 0.254mm) Between Pad P7-0(25.1mm,47.56mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.147mm < 0.254mm) Between Pad P7-0(31.1mm,47.56mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.213mm < 0.254mm) Between Pad P7-0(31.1mm,47.56mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.148mm < 0.254mm) Between Pad TP8-1(8.35mm,2.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.123mm < 0.254mm) Between Pad TP8-1(8.35mm,2.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.148mm < 0.254mm) Between Pad TP8-1(8.35mm,2.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.123mm < 0.254mm) Between Pad TP8-1(9.9mm,2.3mm) on Top Layer And Track

Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.148mm < 0.254mm) Between Pad TP8-1(9.9mm,2.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.148mm < 0.254mm) Between Pad TP8-1(9.9mm,2.3mm) on Top Layer And Track

